BGA Heat Sink - High Performance Device Specific - NXP





ATS Part#: Description:

ATS-59004-C1-R0

32.00 x 50.00 x 12.00 mm BGA Heat Sink - High Performance Device Specific - NXP

Heat Sink Type: NXP Heat Sink Attachment: maxiGRIP Equivalent Part Number: ATS-59004-C2-R0 Discontinued

*Image above is for illustration purpose only.

Features & Benefits

- Designed for flip-chip processors such as NXP MPCs .
- maxiGRIP™ attachment applies steady, even pressure to the component and does not require holes in the PCB .
- Comes preassembled with high performance, phase changing, thermal interface material .

Thermal Performance

AIR VELOCITY		@200 LFM 1.0 M/S	@300 LFM 1.5 M/S	@400 LFM 2.0 M/S	@500 LFM 2.5 M/S	@600 LFM 3.0 M/S	@700 LFM 3.5 M/S	@800 LFM 4.0 M/S
THERMAL RESISTANCE	Unducted Flow	3.2 °C/W	2.46 °C/W	2 °C/W	1.7 °C/W	1.5 °C/W	1.3 °C/W	1.2 °C/W
	Ducted Flow	1.9	N/A	N/A	N/A	N/A	N/A	N/A

Product Detail

32.00 mm50.00 mm12.00 mm80.2 mmT766BLACK-ANODIZEDImage: Constraint of the state o	Schematic Image	Dimension A	Dimension B	Dimension C	Dimension D	ТІМ	Finish			
 Dimension A and B refer to component size. Dimension C is the heat sink height from the bottom of the base to the top of the fin field. ATS-59004-C2-R0 is the exact heat sink assembly with an equivalent thermal interface material (Saint Gobain C1100F). NOTE: Saint Gobain C1100F is discontinued effective 12/31/10. Thermal performance data are provided for reference only. Actual performance may vary by application. ATS reserves the right to update or change its products without notice to improve the design or performance. ATS certifies that this heat sink assembly is RoHS-6 and REACH compliant. Optional maxiGRIP™ Installation/Removal Tool Set P/N: MGT170 		32.00 mm	50.00 mm	12.00 mm	80.2 mm	T766	BLACK-ANODIZED			
*Image above is for illustration purpose only.		 Dimension Dimension ATS-5900 (Saint Go Thermal papplication ATS resepret performant ATS certifier Optional page 	n C is the heat sink I 04-C2-R0 is the exact bain C1100F). NOT performance data ar n. rves the right to upd nce. fies that this heat sir maxiGRIP™ Installa	s the heat sink height from the bottom of the base to the top of the fin field. 2-R0 is the exact heat sink assembly with an equivalent thermal interface material C1100F). NOTE: Saint Gobain C1100F is discontinued effective 12/31/10. Immance data are provided for reference only. Actual performance may vary by the right to update or change its products without notice to improve the design or that this heat sink assembly is RoHS-6 and REACH compliant. IGRIP™ Installation/Removal Tool Set P/N: MGT170						

For more information, to find a distributor or to place an order, please contact us at 781-769-2800 (North America), sales@qats.com or www.qats.com.



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